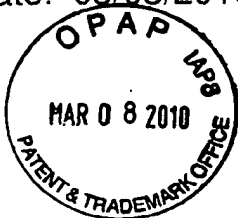


Receipt date: 03/08/2010



DO NOT ENTER: K.A.B./

03/17/2010

RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE

IN THE U.S. PATENT AND TRADEMARK OFFICE

March 4, 2010

*Enter RCB
04/05/10
AS*

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL REJECTION

Sir:

In response to the Office Action dated January 5, 2010,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on March 4, 2010.


Terryence F. Chapman